HN2D02FUTW1T1

Ultra High Speed Switching Diodes

These Silicon Epitaxial Planar Diodes are designed for use in ultra high speed switching applications. These devices are housed in the SC-88 package which is designed for low power surface mount applications.

Features

- Fast t_{rr} , < 3.0 ns
- Low C_D , < 2.0 pF
- Pb-Free Package is Available

MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Rating	Symbol	Value	Unit
Reverse Voltage	V _R	80	V
Peak Reverse Voltage	V_{RM}	85	V
Forward Current (Note 1)	ΙF	100	mAdc
Peak Forward Current (Note 1)	I _{FM}	240	mAdc
Peak Forward Surge Current (10 ms) (Note 1)	I _{FSM}	1.0	Adc

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. This is maximum rating for a single diode. In the case of using 2 or 3 diodes, the maximum ratings per diodes is 75% of the single diode.

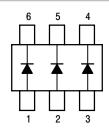
THERMAL CHARACTERISTICS

Rating	Symbol	Max	Unit
Power Dissipation	P _D	300	mW
Junction Temperature	T_J	150	°C
Storage Temperature	T _{stg}	-55 to +150	°C



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SC-88 CASE 419B

MARKING DIAGRAM



R7 = Specific Device Code

M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]		
HN2D02FUTW1T1	SC-88	3000/Tape & Reel		
HN2D02FUTW1T1G	SC-88 (Pb-Free)	3000/Tape & Reel		

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

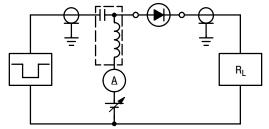
HN2D02FUTW1T1

ELECTRICAL CHARACTERISTICS $(T_A = 25^{\circ}C)$

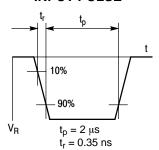
Characteristic	Symbol	Condition	Min	Max	Unit
Reverse Voltage Leakage Current	I _R	V _R = 30 V	-	0.1	μAdc
		V _R = 80 V	-	0.5	
Forward Voltage	V _F	I _F = 100 mA	-	1.2	Vdc
Reverse Breakdown Voltage	V _R	I _R = 100 μA	80	-	Vdc
Diode Capacitance	C _D	V _R = 0, f = 1.0 MHz	-	2.0	pF
Reverse Recovery Time (Figure 1)	t _{rr} (Note 2)	$I_F = 10 \text{ mA}, V_R = 6.0 \text{ V},$ $R_L = 100 \Omega, I_{rr} = 0.1 I_R$	-	3.0	ns

2. t_{rr} Test Circuit

RECOVERY TIME EQUIVALENT TEST CIRCUIT



INPUT PULSE



OUTPUT PULSI

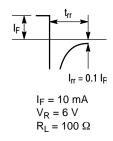
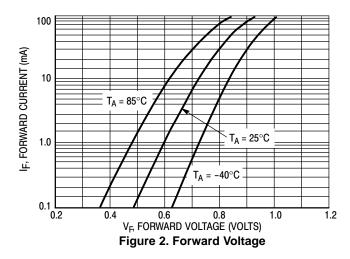
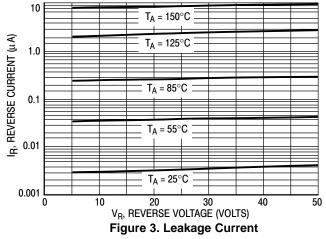
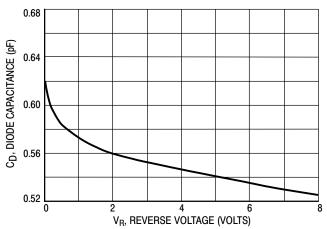


Figure 1. Reverse Recovery Time Equivalent Test Circuit



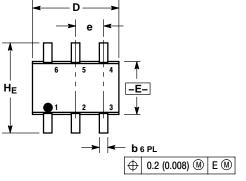




HN2D02FUTW1T1

PACKAGE DIMENSIONS

SC-88 (SOT-363) CASE 419B-02 ISSUE V



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH. 3. 419B-01 OBSOLETE, NEW STANDARD 419B-02.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.80	0.95	1.10	0.031	0.037	0.043
A1	0.00	0.05	0.10	0.000	0.002	0.004
А3	0.20 REF			0.008 REF		
р	0.10	0.21	0.30	0.004	0.008	0.012

 A3
 0.20 REF
 0.008 REF

 b
 0.10
 0.21
 0.30
 0.004
 0.008
 0.012

 C
 0.10
 0.14
 0.25
 0.004
 0.005
 0.010

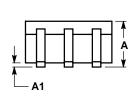
 D
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 2.00
 2.20
 0.070
 0.078
 0.086

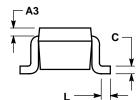
 E
 1.15
 1.25
 1.35
 0.045
 0.049
 0.053

 e
 0.65 BSC
 0.026 BSC

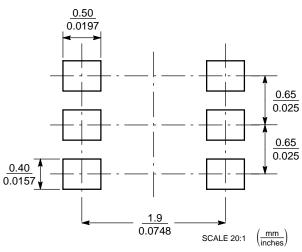
 L
 0.10
 0.20
 0.30
 0.004
 0.008
 0.012

 H_E
 2.00
 2.10
 2.20
 0.078
 0.082
 0.086





SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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